Transmitted herewith for filing is the patent application of under 37 CFR 1.53(b):

INVE	NTOR(S): Chi-Long TSAI; Min-Lung HUANG; Chao-Fu WENG; En-Chieh WU;
	Yang HONG-ZEN
TITL	E: Method For Forming UBM Pads And Bumps On Wafer
	This application is being filed without the declaration of the inventor(s). Inventor information is as follows:
	This is a continuing application of prior Application No/  Continuation  Divisional  Continuation-in-part
<u>x</u>	osed are:  Specification  8    Sheets of drawings (Figs. 1-2)  Oath or Declaration signed by the inventor(s)  X     Newly Executed  Copy of Oath or Declaration from a Prior Application  PLEASE DELETE the following inventor(s) named in the prior non-provisional application:
x x x	English Translation Document Application Data Sheet Large entity status is claimed Preliminary Amendment

23338

PATENT TRADEMARK OFFICE

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Indep. Claims $3 - 3 = x + 43 =$			
Multiple Dependent Claims Presented + \$145 =			
TOTAL \$770			
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